



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN Number: **08-04**

Date Issued: **October 20, 2008**

Product(s) Affected: **Various IC Package Types: TSSOP, LQFP, SSOP, FQFP, QSOP, TQFN**

Manufacturing Location Affected: **Adding Greatek Electronic Inc.'s Taiwan facility to Pericom Approved Vendor Listing for IC products in the package types listed above.**

Date Effective: **November 20, 2008**

Means of Distinguishing Changed Devices:

- Product Mark
- Back Mark
- Date Code **Assembly ID Letter Code "G" \***
- Other \_\_\_\_\_

**\*G – Next to the last letter of the date code marking**

Contact: **Brian Conway, Director of Quality Systems**

Phone: **(408) 435-0800, Ext. 314**

Fax: **(408) 321-0324**

e-Mail: [bconway@pericom.com](mailto:bconway@pericom.com)

Attachment:  Yes;  No

Samples: **Available when requested from Pericom Sales**

Description and Purpose of Change:

**Pericom has added the Greatek Electronics Inc. assembly facility in Taiwan to our qualified supplier list of approved IC package subcontract manufacturers. This action has increased Pericom's manufacturing capacity for products being assembled in TSSOP, LQFP, SSOP, FQFP, QSOP, TQFN Package types.**

**Greatek's facility has achieved certification to ISO-9001:2000, ISO 14001:2004, ISO/TS16949:2002, and the Sony Green Partner Certificate. More information on this supplier is available at Greatek's website: <http://www.greatek.com.tw/>**

**Greatek's manufacturing facility was successfully audited & approved by Pericom earlier this year, and the qualification testing for the various package families are either finished or nearing completion.**

**With the addition of Greatek's manufacturing facility as an approved source for the package families listed above, Pericom is now better able to meet customer demand for our products by building and shipping from any of our approved sources. With this manufacturing strategy, no specific Pericom part numbers can be provided by PCN, as the decision on when, what product, and which approved assembly supplier will be made on an on-going basis by Pericom's Planning department. This flexibility increases manufacturing responsiveness and allows Pericom to better meet customer demand and delivery requirements.**

- Die Technology
- Wafer Fabrication
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other **Added a new IC package assembly site: Greatek Electronics Inc.**

Reliability/Qualification Summary: **Copies of Greatek's package qualification reports will be available on request.**

Customer Acknowledgement of Receipt:

Customer: \_\_\_\_\_

Name: \_\_\_\_\_

Title: \_\_\_\_\_

Date: \_\_\_\_\_

eMail: \_\_\_\_\_

Phone: \_\_\_\_\_

Fax: \_\_\_\_\_

Approval for shipments prior to effective date

Customer Comments (Optional): \_\_\_\_\_